

Product / Package Information

Package	eWLB
Body Size	
I/O Count	75
Terminal Finish	SnAgCu
MS Number	(Rx)

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	6.31 E-03	100.00	1000000	19.73	197350

Wafer Bumps

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	4.39E-03	96.50	965000	13.73	137326
Tin & its alloys	Silver	7440-22-4	1.36E-04	3.00	30000	0.43	4269
Tin & its alloys	Copper	7440-50-8	2.27E-05	0.50	5000	0.071	712
Subtotal			4.55E-03	100.00	1000000	14.23	142307

RDL

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	1.23 E-03	99.31	993134	3.85	38494
Other inorganic materials	Titanium	7440-32-6	8.50E-07	0.07	687	0.003	27
Other non-ferrous metals and alloys	Tungsten	7440-33-7	7.65E-06	0.62	6179	0.024	240
Subtotal			1.24 E-03	100.00	1000000	3.88	38761

Polyimide 1

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other organic materials	Ethyl Lactate	97-64-3	4.27 E-05	53.66	536585	0.13	1337
Other organic materials	Thermoset Resin	Proprietary	2.02 E-05	25.37	253659	0.063	632
Other organic materials	Additive	Proprietary	1.36 E-05	17.07	170732	0.043	425
Other organic materials	Modified Thermoset Resin	Proprietary	3.11 E-06	3.90	39024	0.010	97
Subtotal			7.96E-05	100.00	1000000	0.25	2491

Polyimide 2

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other organic materials	Polyamic Acid Ester	Proprietary	1.61 E-05	61.90	619048	0.05	505
Other organic materials	Ethyl Lactate	Proprietary	6.20 E-06	23.81	238095	0.02	194
Other organic materials	Tetraethyleneglycol Dimethacrylate	109-17-1	1.24 E-06	4.76	47619	0.004	39
Others	Others	Proprietary	2.48 E-06	9.52	95238	0.008	78
Subtotal			2.60 E-05	100.00	1000000	0.08	815

Mold Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	Proprietary	1.77 E-02	89.48	894800	55.32	553234
Thermoplastic	1,6-Bis(2,3-epoxy propoxy)naphthalene	27610-48-6	1.04 E-03	5.26	52600	3.25	32521
Thermoplastic	Methylhexhydrophthalic Anhydride	25550-51-0	1.04 E-03	5.26	52600	3.25	32521
Subtotal			1.98 E-02	100.00	1000000	61.83	618276

Package Totals	Weight (g)	Percentage (%)	PPM
	3.20 E-02	100.00	1000000

Note: The information provided in this declaration are true to the best of ADI's knowledge. ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.



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